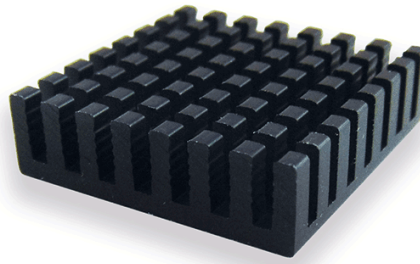


Product features PG

2828/8/SE/SF

Semiconductor casing:	PGA ; BGA ; IC
Semiconductor mounted by:	Bonding
Heat sink mounted by:	Adhesive Bounding
Finish	Black Anodised
Material	AlMgSi0,5
Width [mm]:	28.0
Height [mm]:	8.0
Length [mm]:	28.0
Min. thermal resistance [K/W]:	11.0



Further information

- Heatsinks for microprocessors (Extrusion Technology) - Direct mounting with self-adhesive foil - Best possible heat radiation from black anodized surface - RthKvalues apply to natural convection (without external ventilation) - Arrangement and number of pins for optimal air flow - Even heat distribution in the base and the pins in the direction of heat flow - Suitable for forced and free convection - Aluminium alloy Al MgSi 0.5 - Thermal conductivity: 180-200 W / mK - Other dimensions and surface finishes by request

